

FORM PTO 1449 (modified) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary)			ATTY DOCKET NO. <b>35.C15514</b>	APPLICATION NO. <b>09/845,286</b>			
			APPLICANT <b>TADAYASU MEGURO ET AL.</b>				
			FILING DATE <b>May 1, 2001</b>	GROUP <b>2879</b>			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>TSP</i>		6,208,071	3/27/01	Nishimura et al.	313	495	
<i>TSP</i>		4,954,744	9/4/90	Suzuki et al.	313	336	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO/ OR ABSTRACT
<i>TSP</i>	EP	0850892	7/98	EPO			(In English)
<i>TSP</i>		10-241550	9/98	Japan			Abstract and USP 6208071
<i>TSP</i>		8-180801	7/96	Japan			Abstract
OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)							
<i>TSP</i>		M.I. Elinson et al., "The Emission of Hot Electrons and The Field Emission of Electrons From Tin Oxide", Radio Engineering and Electronic Physics, July 1965, pp. 1290-1296.					
		H. Araki, "Electroforming and Electron Emission of Carbon Thin Films", Journal of the Vacuum, Society of Japan, 1983, pp. 22-29 (with English-language abstract on page 22).					
		G. Dittmer, "Electrical Conduction and Electron Emission of Discontinuous Thin Films", Thin Solid Films, 9, 1972, pp. 317-328.					
		M. Hartwell, "Strong Electron Emission From Patterned Tin-Indium Oxide Thin Films", IEDM, 1975, pp. 519-521.					
		C.A. Spindt, "Physical Properties of Thin-Film Emission Cathodes with Molybdenum Cones", J. Applied Physics, Vol. 47, No. 12, December 1976, pp. 5248-5263.					
		J. Dyke et al., "Field Emission", Advances in Electronics and Electron Physics, Vol. VIII, 1956, pp. 89-185.					
EXAMINER		<i>THANH S. PHAN</i>		DATE CONSIDERED	<i>3/18/02</i>		

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.